

AO7800

Dual N-Channel Enhancement Mode Field Effect Transistor

General Description

The AO7800 uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 1.8V, in the small SOT363 footprint. It can be used for a wide variety of applications, including load switching, low current inverters and low current DC-DC converters. It is ESD protected.

Features

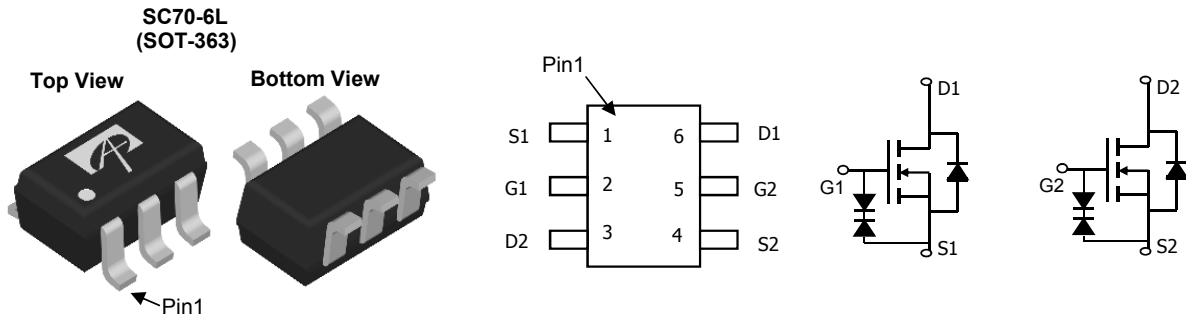
$$V_{DS} (V) = 20V$$

$$I_D = 0.9 A (V_{GS} = 4.5V)$$

$$R_{DS(ON)} < 300m\Omega (V_{GS} = 4.5V)$$

$$R_{DS(ON)} < 350m\Omega (V_{GS} = 2.5V)$$

$$R_{DS(ON)} < 450m\Omega (V_{GS} = 1.8V)$$



Absolute Maximum Ratings $T_A=25^\circ C$ unless otherwise noted

Parameter	Symbol	Maximum	Units	
Drain-Source Voltage	V_{DS}	20	V	
Gate-Source Voltage	V_{GS}	± 8	V	
Continuous Drain Current ^A	I_D	$T_A=25^\circ C$	A	
		$T_A=70^\circ C$		0.7
		Pulsed Drain Current ^B		I_{DM}
Power Dissipation ^A	P_D	$T_A=25^\circ C$	W	
		$T_A=70^\circ C$		0.6
Junction and Storage Temperature Range	T_J, T_{STG}	-55 to 150	$^\circ C$	

Thermal Characteristics

Parameter	Symbol	Typ	Max	Units
Maximum Junction-to-Ambient ^A	$R_{\theta JA}$	120	145	$^\circ C/W$
$t \leq 10s$				
Maximum Junction-to-Ambient ^A	$R_{\theta JL}$	130	150	$^\circ C/W$
Steady-State				
Maximum Junction-to-Lead ^C				

Electrical Characteristics (T_J=25°C unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
STATIC PARAMETERS						
BV _{DSS}	Drain-Source Breakdown Voltage	I _D =250μA, V _{GS} =0V	20			V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =16V, V _{GS} =0V T _J =55°C			1 5	μA
I _{GSS}	Gate-Body leakage current	V _{DS} =0V, V _{GS} =±8V			25	μA
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =250μA	0.5	0.75	0.9	V
I _{D(ON)}	On state drain current	V _{GS} =4.5V, V _{DS} =5V	5			A
R _{DS(ON)}	Static Drain-Source On-Resistance	V _{GS} =4.5V, I _D =0.9A T _J =125°C		181 253	300 350	mΩ
		V _{GS} =2.5V, I _D =0.75A		237	350	mΩ
		V _{GS} =1.8V, I _D =0.7A		317	450	mΩ
g _{FS}	Forward Transconductance	V _{DS} =5V, I _D =0.8A		2.6		S
V _{SD}	Diode Forward Voltage	I _S =0.5A, V _{GS} =0V		0.69	1	V
I _S	Maximum Body-Diode Continuous Current				0.4	A
DYNAMIC PARAMETERS						
C _{iss}	Input Capacitance	V _{GS} =0V, V _{DS} =10V, f=1MHz		101	120	pF
C _{oss}	Output Capacitance		17		pF	
C _{rss}	Reverse Transfer Capacitance		14		pF	
R _g	Gate resistance	V _{GS} =0V, V _{DS} =0V, f=1MHz		3	4	Ω
SWITCHING PARAMETERS						
Q _g	Total Gate Charge	V _{GS} =4.5V, V _{DS} =10V, I _D =0.8A		1.57	1.9	nC
Q _{gs}	Gate Source Charge		0.13		nC	
Q _{gd}	Gate Drain Charge		0.36		nC	
t _{D(on)}	Turn-On DelayTime	V _{GS} =5V, V _{DS} =10V, R _L =12.5Ω, R _{GEN} =6Ω		3.2		ns
t _r	Turn-On Rise Time		4		ns	
t _{D(off)}	Turn-Off DelayTime		15.5		ns	
t _f	Turn-Off Fall Time		2.4		ns	
t _{rr}	Body Diode Reverse Recovery Time	I _F =0.8A, di/dt=100A/μs		6.7	8.1	ns
Q _{rr}	Body Diode Reverse Recovery Charge	I _F =0.8A, di/dt=100A/μs		1.6		nC

A: The value of R_{θJA} is measured with the device mounted on 1in² FR-4 board with 2oz. Copper, in a still air environment with T_A=25° C. The value in any given application depends on the user's specific board design. The current rating is based on the t ≤ 10s thermal resistance rating.

B: Repetitive rating, pulse width limited by junction temperature.

C. The R_{θJA} is the sum of the thermal impedance from junction to lead R_{θJL} and lead to ambient.

D. The static characteristics in Figures 1 to 6,12,14 are obtained using 80 μs pulses, duty cycle 0.5% max.

E. These tests are performed with the device mounted on 1 in² FR-4 board with 2oz. Copper, in a still air environment with T_A=25° C. The SOA curve provides a single pulse rating.

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TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

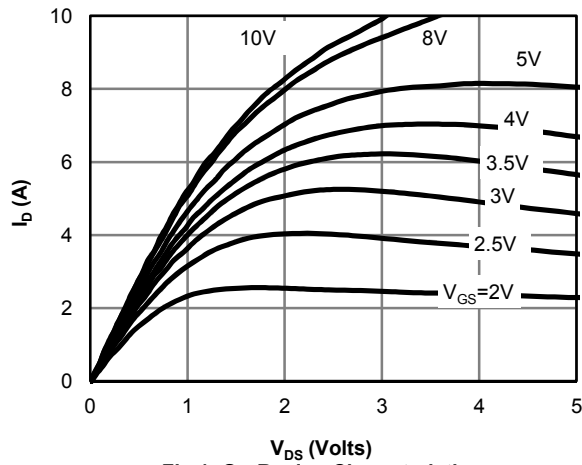


Fig 1: On-Region Characteristics

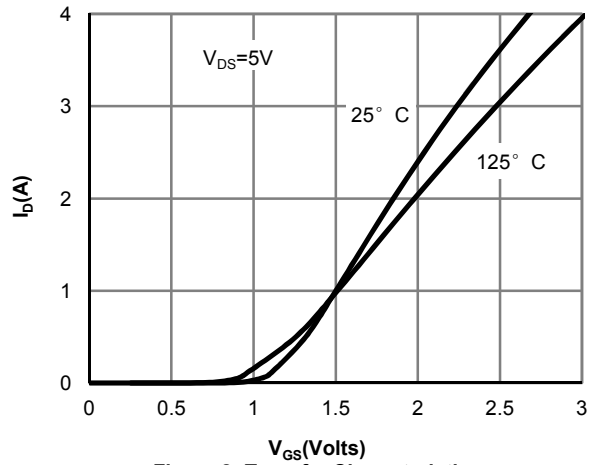


Figure 2: Transfer Characteristics

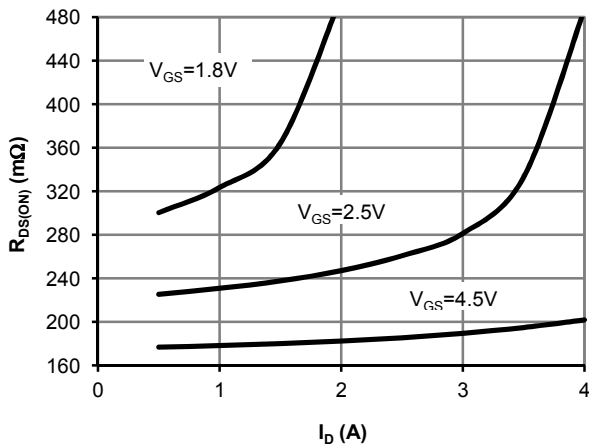


Figure 3: On-Resistance vs. Drain Current and Gate Voltage

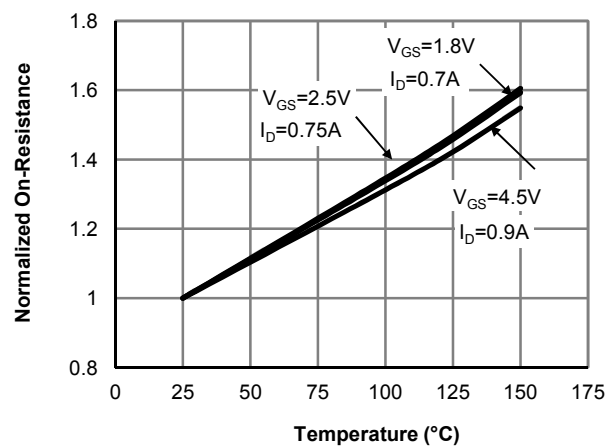


Figure 4: On-Resistance vs. Junction Temperature

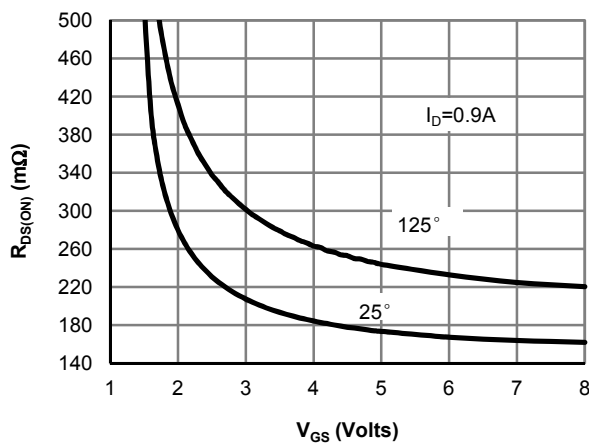


Figure 5: On-Resistance vs. Gate-Source Voltage

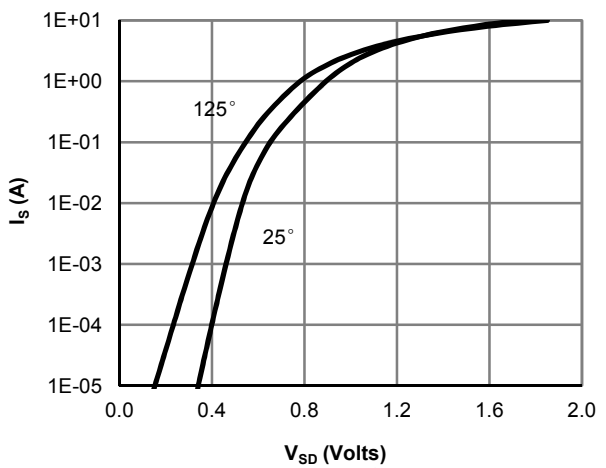


Figure 6: Body-Diode Characteristics

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

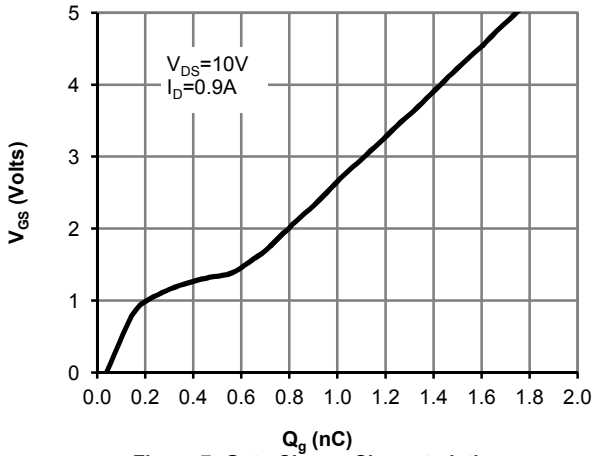


Figure 7: Gate-Charge Characteristics

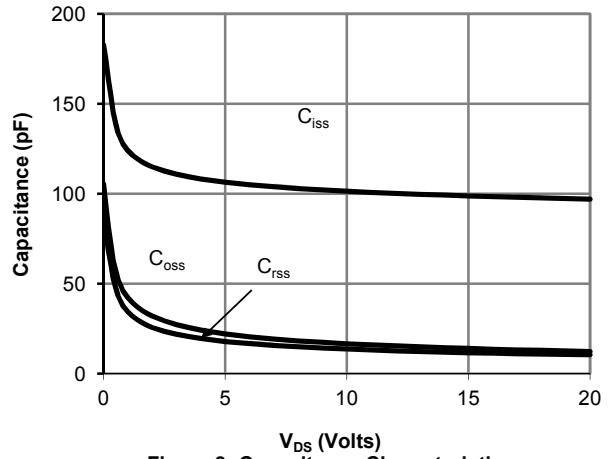


Figure 8: Capacitance Characteristics

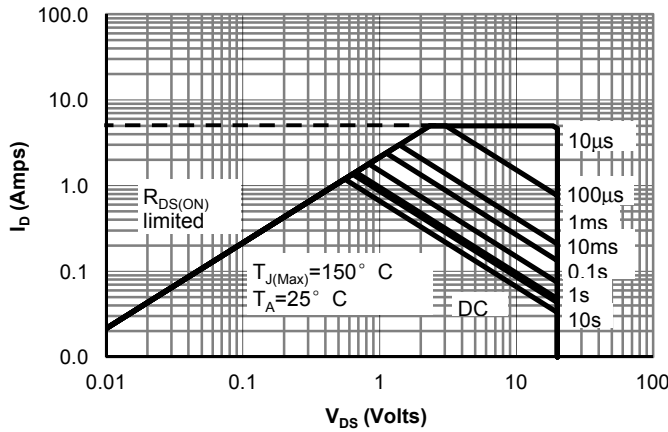


Figure 9: Maximum Forward Biased Safe Operating Area (Note E)

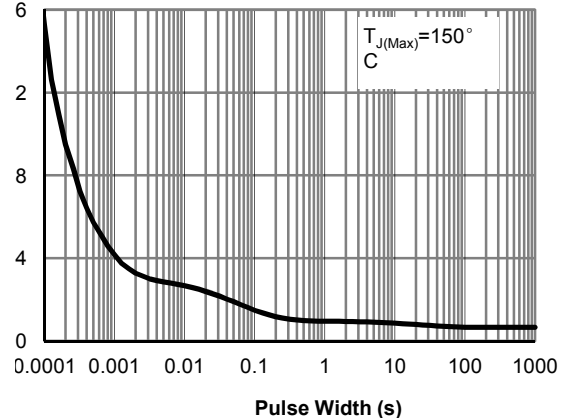


Figure 10: Single Pulse Power Rating Junction-to-Ambient (Note E)

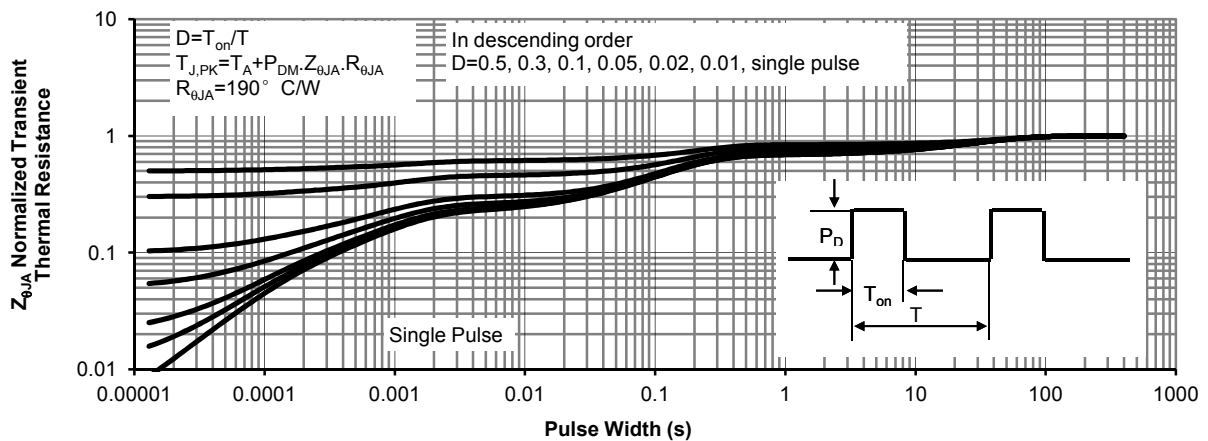
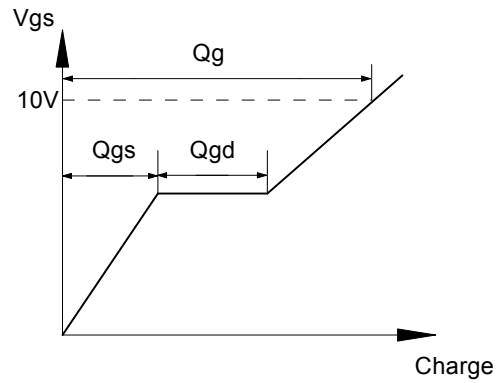
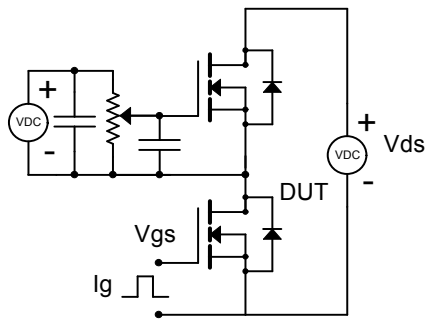
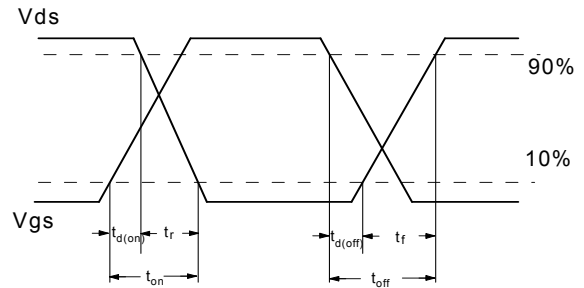
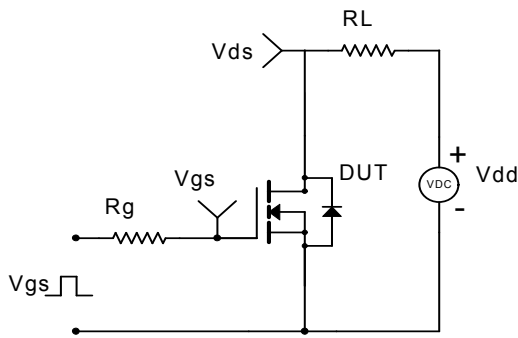


Figure 11: Normalized Maximum Transient Thermal Impedance

Gate Charge Test Circuit & Waveform



Resistive Switching Test Circuit & Waveforms



Diode Recovery Test Circuit & Waveforms

